

ABSTRACT OF THE DISCLOSURE

A semiconductor device connecting structure for connecting a semiconductor IC 7 onto a substrate 13. A bonding layer 31 is placed between the substrate 13 and the semiconductor IC 7 to accomplish adhesion therein. This bonding layer includes an ACF 32 as a bonding material for joining said semiconductor IC 7 onto said substrate 13 and a space 33 formed within the ACF 32. Even if the IC 7 deforms due to heat or the like, the deformation is absorbed by the space 33, whereupon the connecting conditions of bumps 28, 29 can not be unstable.

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